



TAI-SAW TECHNOLOGY CO., LTD.

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Product Specifications Approval Sheet

Product Description: DR Filter 5235MHz (BW=180MHz) 8.6x4.05X3.0

TST Parts No.: TR0007B

Customer Parts No.: _____

| |
|--|
| <p>Company: _____</p> <p>Division: _____</p> <p>Approved by : _____</p> <p>Date: _____</p> |
|--|

Checked by: _____ Hong Pu Lin *Hong Pu Lin*

Approval by: _____ Andy Yu *Andy Yu*

Date: _____ 6 / 13 / 2018

1. Customer signed back is required before TST can proceed with sample build and receive orders.
2. Orders received without customer signed back will be regarded as agreement on the specifications.
3. Any specifications changes must be approved upon by both parties and a new revision of specifications shall be released to reflect the changes.



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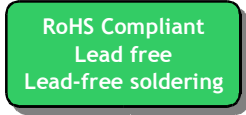
DR Filter 5235MHz 180MHz BW

MODEL NO.: TR0007B

REV. NO.1

A. MAXIMUM RATING:

1. Operating temperature range: -40°C to 85°C
2. Storage temperature range: -40°C to 85°C
3. Input Power Level : 1W
4. Input/Output Impedance:50 Ohm
5. Moisture Sensitive Level: Level 1 (MSL1)

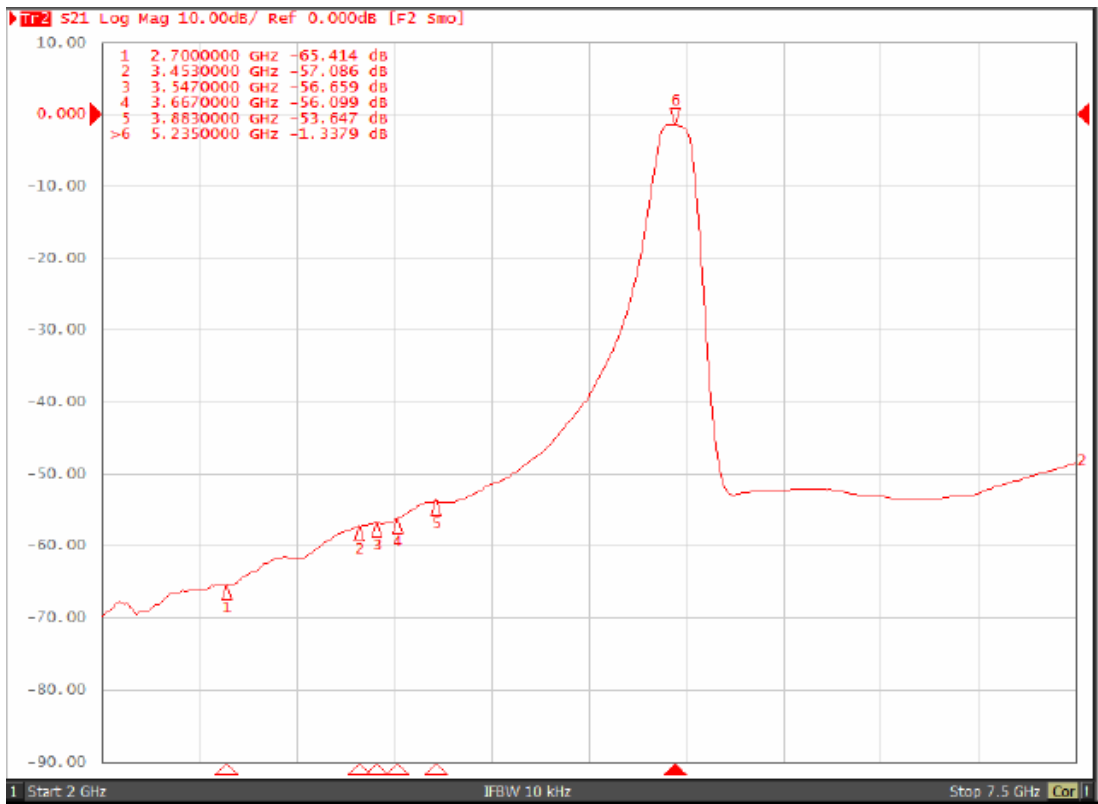
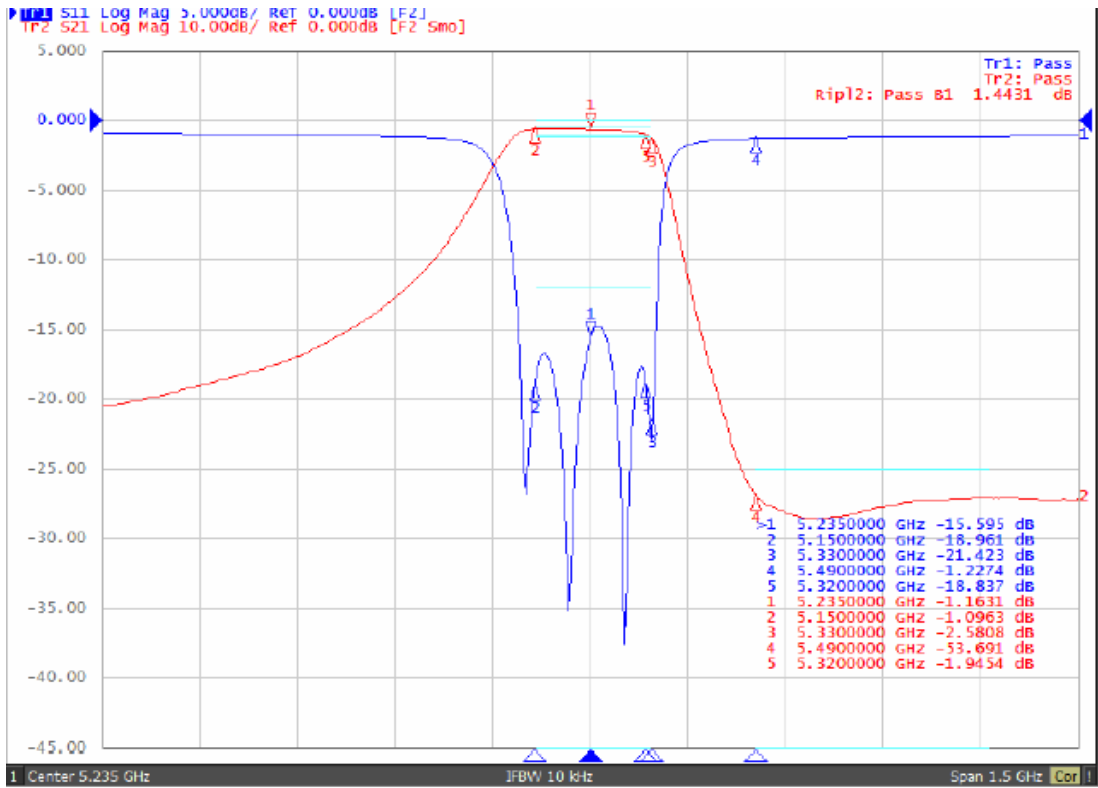


Electrostatic Sensitive Device

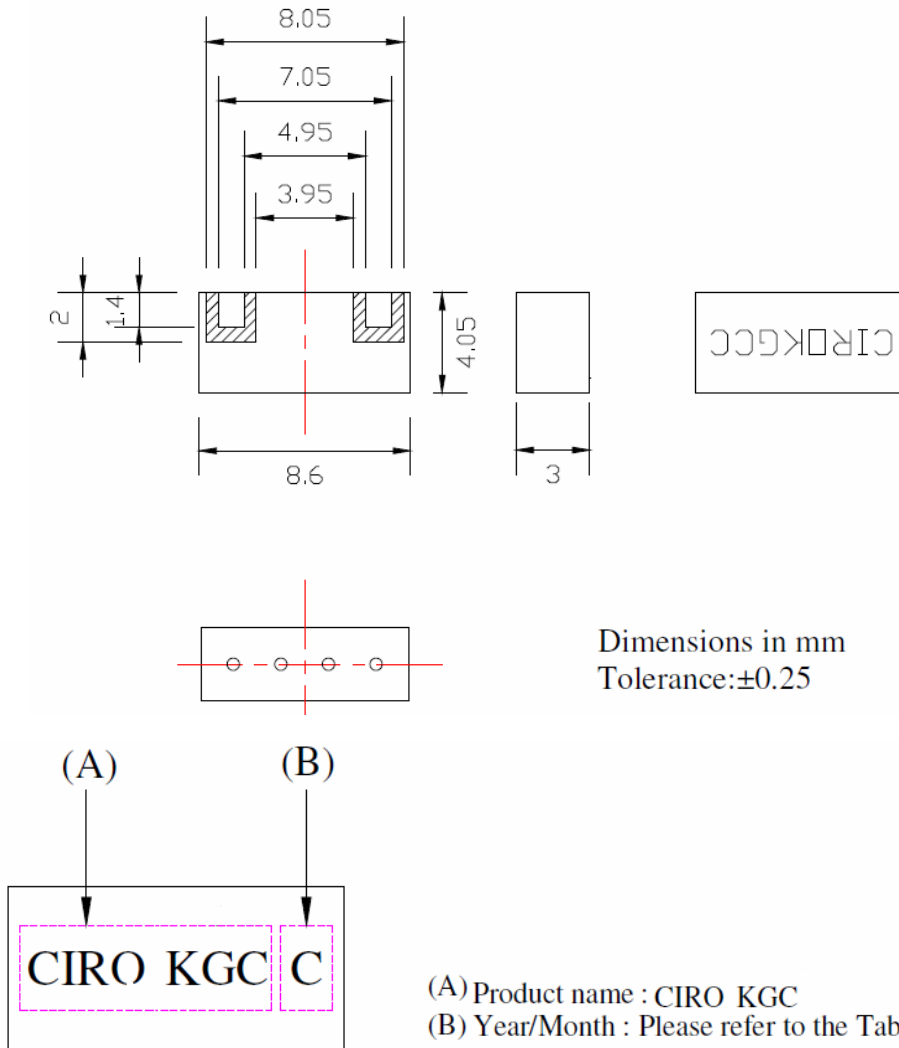
B. CHARACTERISTICS:

| Item | Unit | Min | Type | Max |
|--|------|-----|------|-----|
| Center frequency, Fc | MHz | - | 5235 | - |
| Insertion Loss(5150~5320MHz) | dB | - | 2.0 | 2.5 |
| Insertion Loss(5320~5330MHz) | dB | - | 2.5 | 3.0 |
| Ripple (5150~5330MHz) | dB | - | 1.0 | 1.8 |
| Return Loss (5150~5330MHz) | dB | - | 14 | 10 |
| Specifies the absolute value of Attenuation | | | | |
| 30~2700MHz | dB | 38 | 65 | - |
| 3453~3547MHz | dB | 16 | 56 | - |
| 3667~3883MHz | dB | 33 | 53 | - |
| 5490~5850MHz | dB | 50 | 53 | - |
| 7200~7500MHz | dB | 20 | 46 | - |

C. FREQUENCY CHARACTERISTICS:

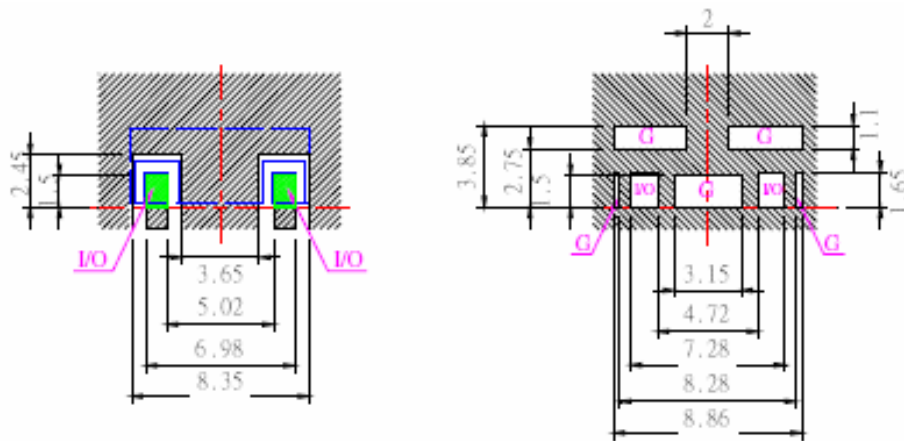


D. OUTLINE DRAWING:



(Table-1)

| Year | Month | Code | Year | Month | Code | Year | Month | Code | Year | Month | Code |
|------------------------------|-------|------|------------------------------|-------|------|------------------------------|-------|------|------------------------------|-------|------|
| 2012 2016 2020 2024 | 1 | A | 2013 2017 2021 2025 | 1 | N | 2014 2018 2022 2026 | 1 | A. | 2015 2019 2023 2027 | 1 | N. |
| | 2 | B | | 2 | P | | 2 | B. | | 2 | P. |
| | 3 | C | | 3 | Q | | 3 | C. | | 3 | Q. |
| | 4 | D | | 4 | R | | 4 | D. | | 4 | R. |
| | 5 | E | | 5 | S | | 5 | E. | | 5 | S. |
| | 6 | F | | 6 | T | | 6 | F. | | 6 | T. |
| | 7 | G | | 7 | U | | 7 | G. | | 7 | U. |
| | 8 | H | | 8 | V | | 8 | H. | | 8 | V. |
| | 9 | J | | 9 | W | | 9 | J. | | 9 | W. |
| | 10 | K | | 10 | X | | 10 | K. | | 10 | X. |
| | 11 | L | | 11 | Y | | 11 | L. | | 11 | Y. |
| | 12 | M | | 12 | Z | | 12 | M. | | 12 | Z. |



Tolerance ± 0.20

I/O : Input/Output

G : Ground



Electrode



Solder Resist

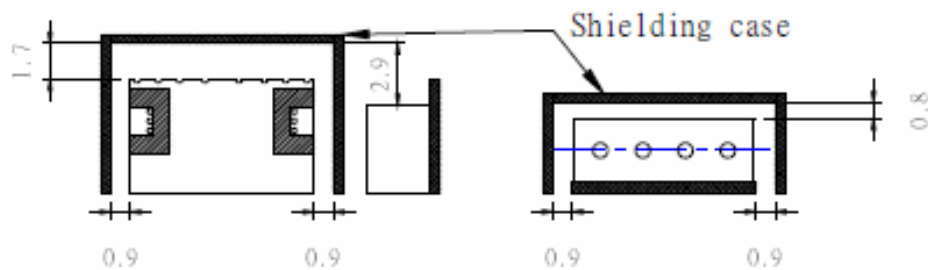


I/O Pads must be connected to lines with 50Ω impedance. In the application a termination of 50Ω must be realized.

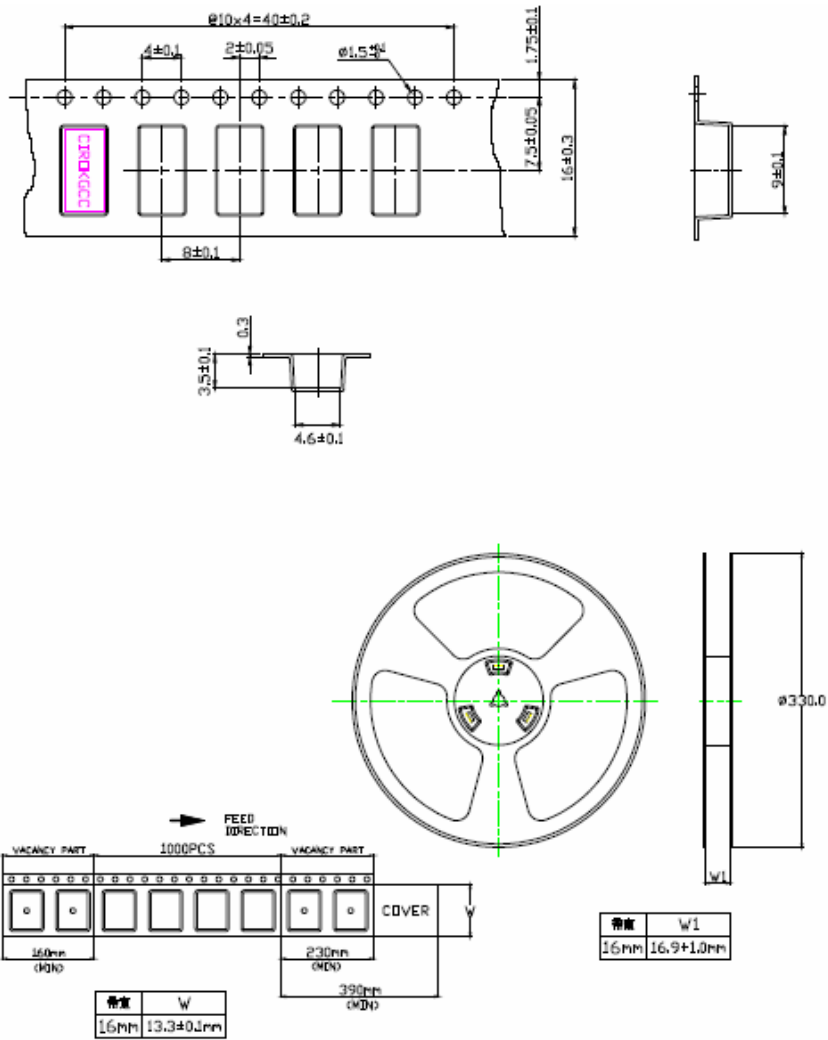


Solder LAND

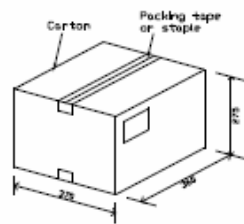
Shielding case layout guide (min)



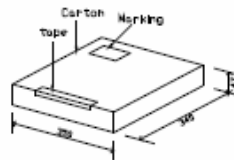
E. PACKING:



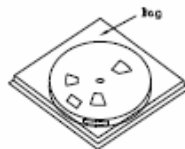
1. Outer Carton
Quantity: 5000PCS



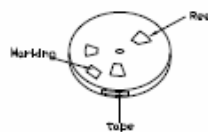
2. Inner Carton
Quantity: 1000PCS



3. Bag
Quantity: 1000PCS



4. Taping
Quantity: 1000PCS



Unit:mm

F. RECOMMENDED REFLOW PROFILE:

| Phase | Profile features | Pb-Free Assembly (SnAgCu) |
|------------------------------------|---|----------------------------------|
| PREHEAT | -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(ts) form (T_{smin} to T_{smax}) | 150°C 200°C 60-120 seconds |
| RAMP-UP | Avg. Ramp-up Rate (T_{smax} to TP) | 3°C/second(max) |
| REFLOW | -Temperature(T_L) -Total Time above T_L (t_L) | 217°C 30-100 seconds |
| PEAK | -Temperature(T_P) -Time(t_p) | 260°C 3 second |
| RAMP-DOWN | Rate | 6°C / second max. |
| Time from 25°C to Peak Temperature | | 8 minutes max. |
| Composition of solder paste | | 96.5Sn/3Ag/0.5Cu |
| Solder Paste Model | | SHENMAO PF606-P26 |

The graphic shows temperature profile for component assembly process in reflow ovens

